

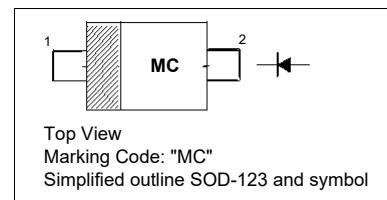
## MBR130W Surface Mount Schottky Barrier Diode

### Features

- Low Forward Voltage
- Package Designed for Optimal Automated Board Assembly

### PINNING

PIN	DESCRIPTION
1	Cathode
2	Anode



### Absolute Maximum Ratings ( $T_a = 25^\circ\text{C}$ )

Parameter	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	$V_{RRM}$	30	V
Working Peak Reverse Voltage	$V_{RWM}$	30	V
DC Blocking Voltage	$V_R$	30	V
Average Rectified Forward Current (Rated $V_R$ ) $T_L = 65^\circ\text{C}$	$I_{F(AV)}$	1	A
Non-Repetitive Peak Forward Surge Current (Surge Applied at Rated Load Conditions, Halfwave, Single Phase, 60 Hz)	$I_{FSM}$	5.5	A
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	230 <sup>1)</sup>	$^\circ\text{C}/\text{W}$
Thermal Resistance, Junction to Lead	$R_{\theta JL}$	108 <sup>1)</sup>	$^\circ\text{C}/\text{W}$
Operating Junction Temperature	$T_j$	- 65 to + 125	$^\circ\text{C}$
Storage Temperature Range	$T_{stg}$	- 65 to + 125	$^\circ\text{C}$

<sup>1)</sup>FR-4 or FR-5 = 3.5 X 1.5 inches using a 1 inch Cu pad.

### Characteristics at $T_a = 25^\circ\text{C}$

Parameter	Symbol	Min.	Max.	Unit
Forward Voltage at $I_F = 0.1 \text{ A}$ at $I_F = 0.7 \text{ A}$	$V_F$	- -	0.35 0.5	V
Reverse Breakdown Voltage at $I_R = 1 \text{ mA}$	$V_{(BR)R}$	30	-	V
Reverse Current at $V_R = 30 \text{ V}$ at $V_R = 5 \text{ V}$	$I_R$	- -	200 50	$\mu\text{A}$

## Typical Characteristics

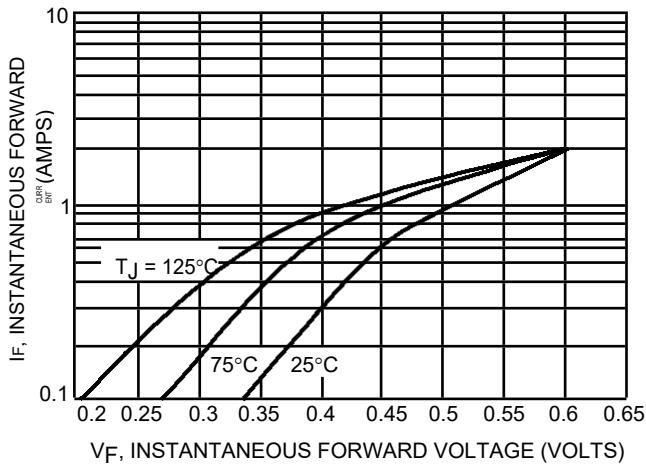


Figure 1. Maximum Forward Voltage

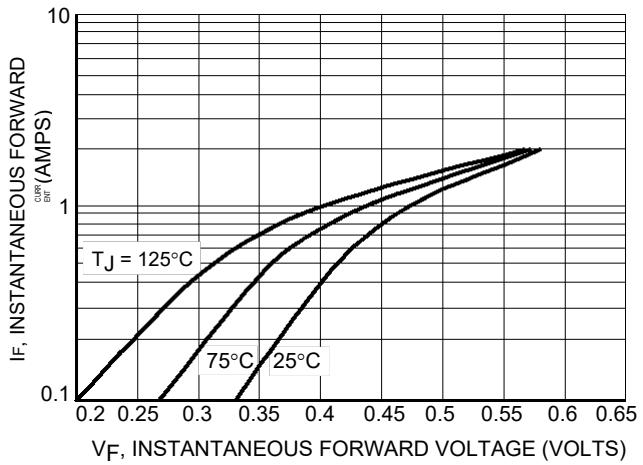


Figure 2. Typical Forward Voltage

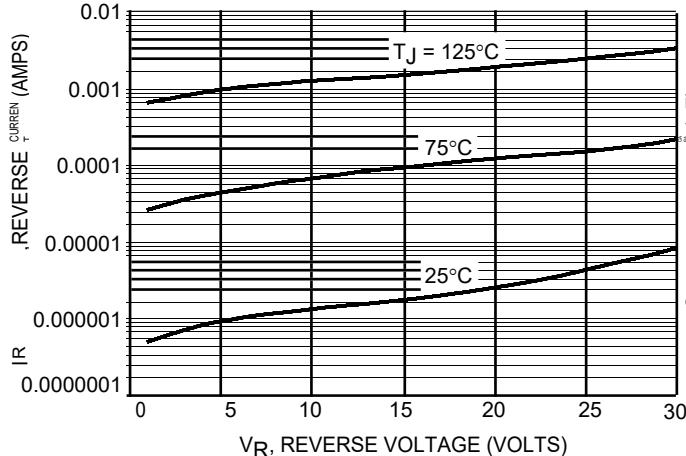


Figure 3. Typical Reverse Current

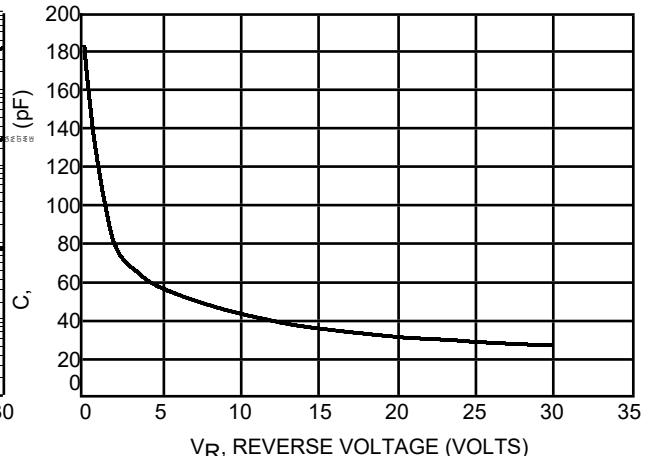


Figure 4. Typical Capacitance

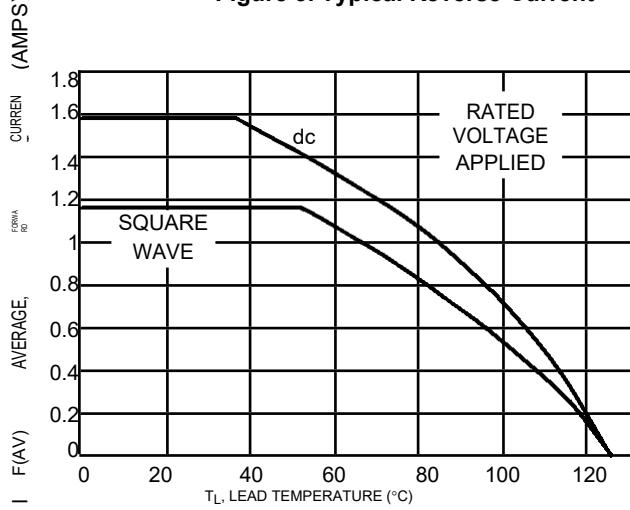


Figure 5. Current Derating, Lead,  $R_{JL} = 108 \text{ C/W}$

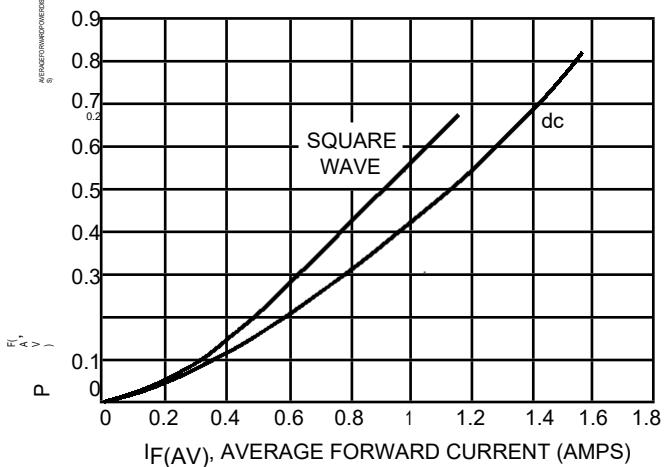
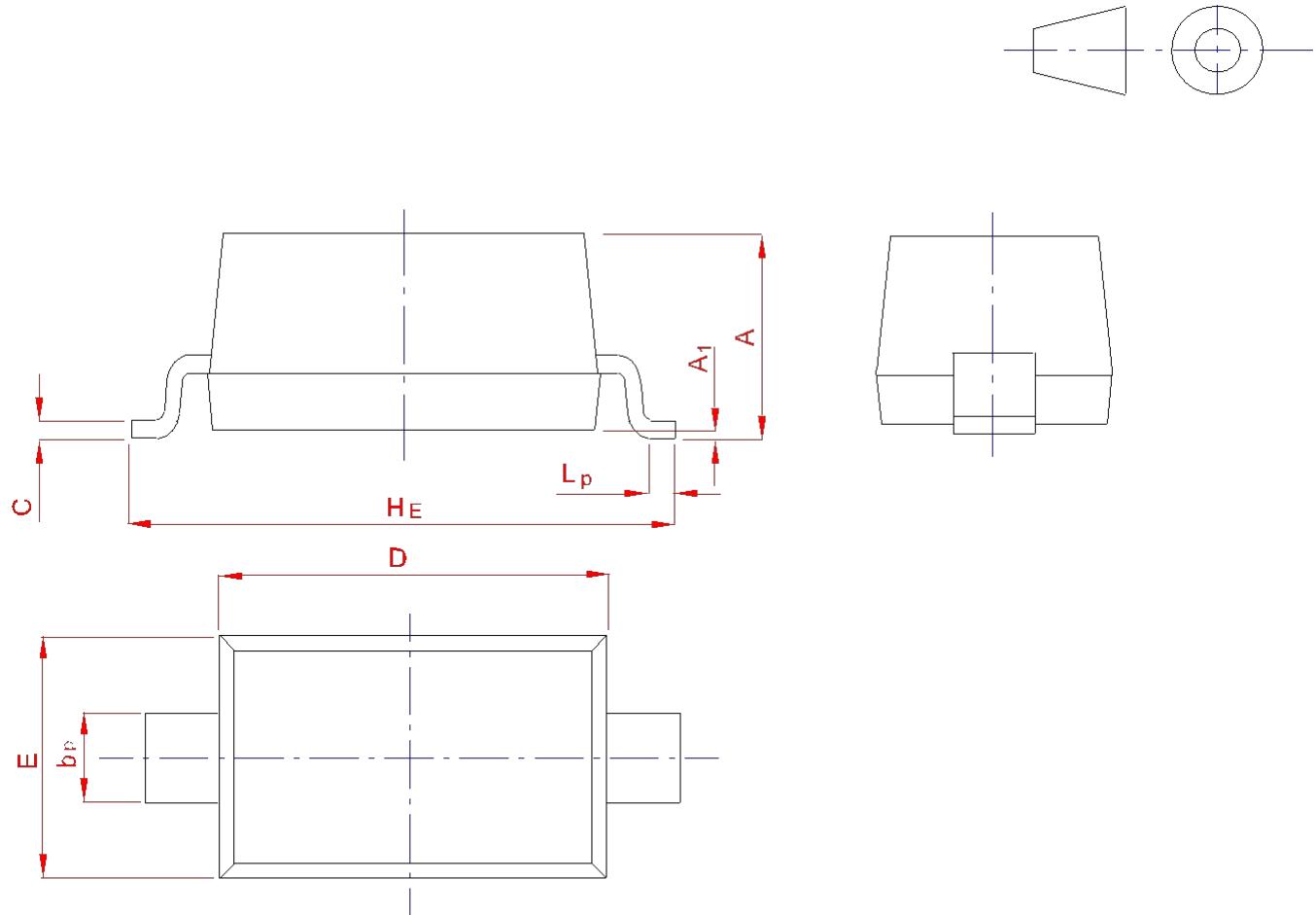


Figure 6. Forward Power Dissipation

## PACKAGE OUTLINE

Plastic surface mounted package; 2 leads

SOD-123



UNIT	A	b <sub>p</sub>	C	D	E	H <sub>E</sub>	A <sub>1</sub>	L <sub>p</sub>
mm	1.20 0.90	0.60 0.50	0.135 0.100	2.75 2.55	1.65 1.55	3.85 3.55	0.10 0.01	0.50 0.20